

P-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY

V _{DS} (V)	R _{DS(on)} (mΩ)(Typ.)	I _D (A) ^a	Q _g (Typ.)
-20	23 at V _{GS} = -4.5 V	- 8	15 nC
	32 at V _{GS} = -2.5 V		

FEATURES

- DT-Trench Power MOSFET
- 100 % R_g and UIS Tested

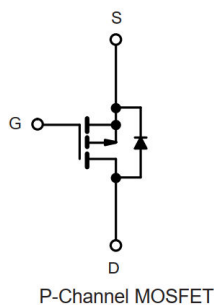
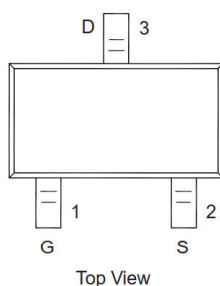
APPLICATIONS

- Power Management for Portable and Consumer
 - Load Switches
 - DC/DC Converters



RoHS
COMPLIANT

(SOT-23-3L)



ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	-20	V
Gate-Source Voltage	V _{GS}	± 12	
Continuous Drain Current (T _J = 150 °C)	I _D	T _C = 25 °C -8	A
		T _C = 100 °C -6	
Pulsed Drain Current	I _{DM}	-32	
Maximum Power Dissipation	P _D	T _C = 25 °C 2.5 ^{b, c}	W
		T _C = 100 °C 1.2 ^{b, c}	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C
Soldering Recommendations (Peak Temperature)		260	

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{b, d}	R _{thJA}	-	82	°C/W
Maximum Junction-to-Case (Drain)	R _{thJC}	-	2.2	

Notes:

a. T_C = 25 °C.

b. Surface mounted on 1" x 1" FR4 board.

c. t = 5 s.

d. Maximum under steady state conditions is 100C/W.

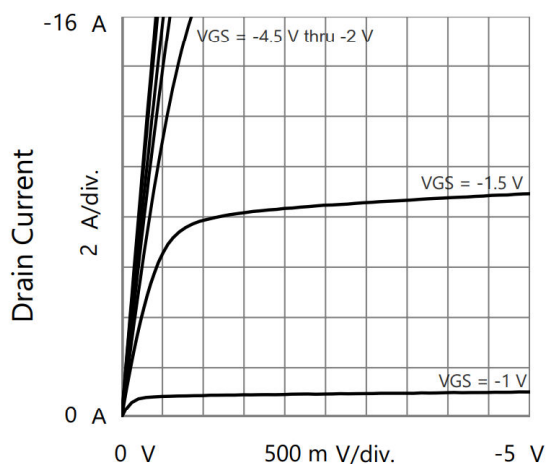
SPECIFICATIONS T _J = 25 °C, unless otherwise noted						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA	- 20			V
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = - 250 μA	- 0.4		-1.0	V
Gate-Source Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 12 V			± 10	μA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 20 V, V _{GS} = 0 V			- 1	
		V _{DS} = - 20 V, V _{GS} = 0 V, T _J = 55 °C			- 10	
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≤ - 5 V, V _{GS} = - 4.5 V	- 8			A
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 5 A		23	27	mΩ
		V _{GS} = - 2.5 V, I _D = - 5 A		32	40	
Forward Transconductance ^a	g _{fs}	V _{DS} = - 4.5 V, I _D = - 5 A		9		S
Dynamic ^b						
Input Capacitance	C _{iss}	V _{DS} = - 10 V, V _{GS} = 0 V, f = 1 MHz		1510		pF
Output Capacitance	C _{oss}			180		
Reverse Transfer Capacitance	C _{rss}			158		
Total Gate Charge	Q _g	V _{DS} = - 10 V, V _{GS} = - 4.5 V, I _D = - 5 A		15		nC
Gate-Source Charge	Q _{gs}			1.8		
Gate-Drain Charge	Q _{gd}			2.8		
Gate Resistance	R _g	f = 1 MHz		15		Ω
Turn-On Delay Time	t _{d(on)}	V _{DD} = - 10 V, R _L = 10 Ω I _D ≅ - 5 A, V _{GEN} = - 4.5 V, R _g = 6 Ω		4.5		ns
Rise Time	t _r			9		
Turn-Off DelayTime	t _{d(off)}			18		
Fall Time	t			3		
Drain-Source Body Diode Characteristics						
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			-8	A
Pulse Diode Forward Current	I _{SM}				-32	
Body Diode Voltage	V _{SD}	I _S = - 1 A, V _{GS} = 0 V		-0.6	-1.2	V
Body Diode Reverse Recovery Time	t _{rr}	I _F = -5 A, dI/dt = 100 A/μs, T _J = 25 °C		13	24	ns
Body Diode Reverse Recovery Charge	Q _{rr}			7	15	nC
Reverse Recovery Fall Time	t _a			9		ns
Reverse Recovery Rise Time	t _b			7		

Notes:

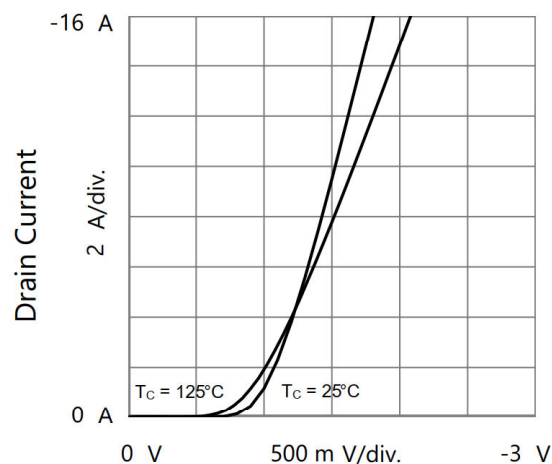
- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
 b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

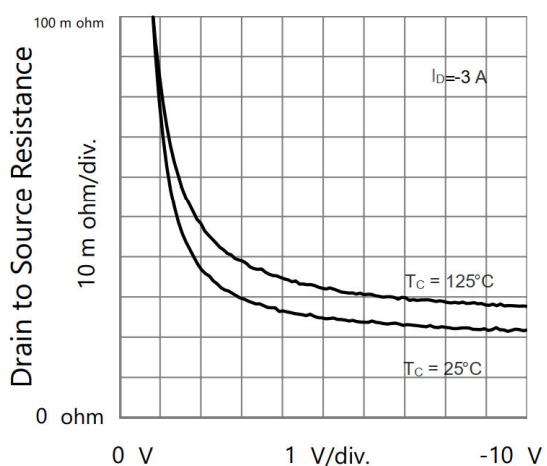
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



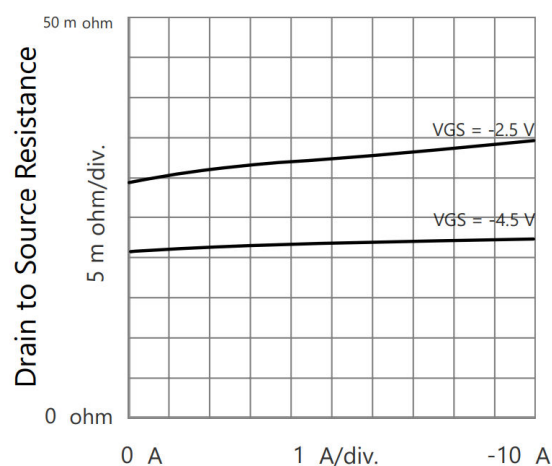
Drain to Source Voltage
Output Characteristics



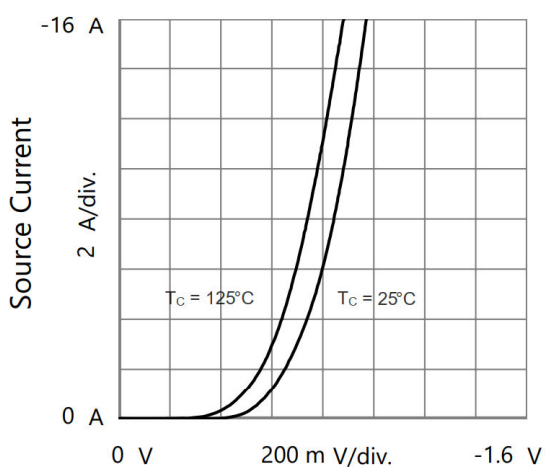
Gate to Source Voltage
Transfer Characteristics



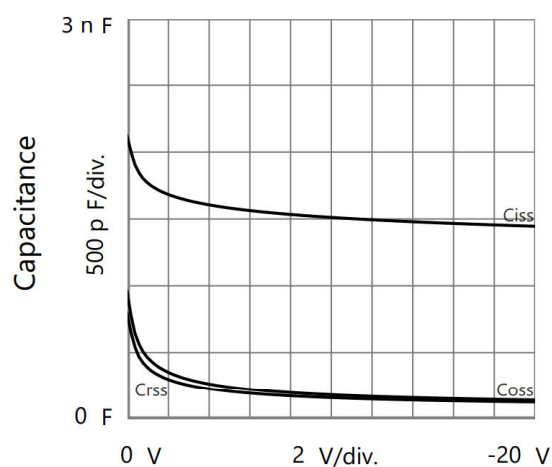
Gate to Source Voltage
Drain to Source Resistance vs. Gate to Source Voltage



Drain Current
Drain to Source Resistance vs. Drain Current

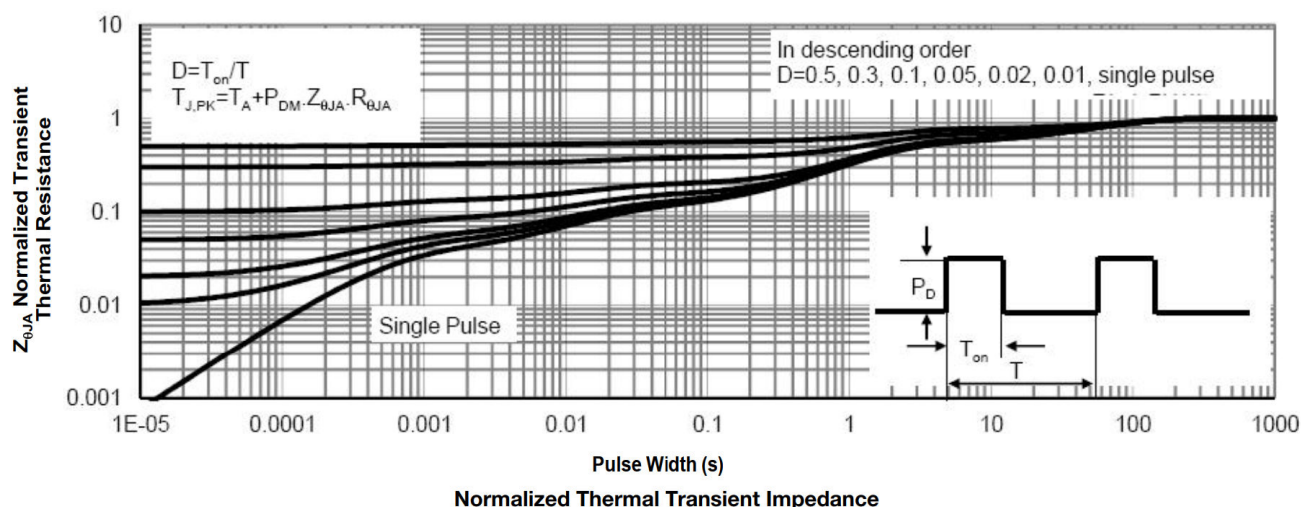
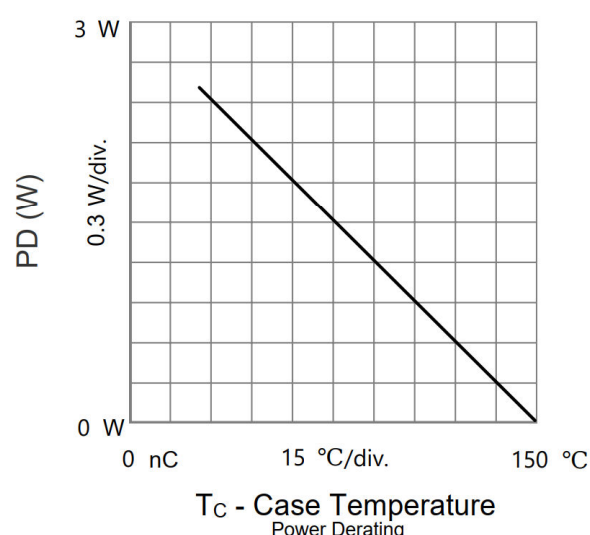
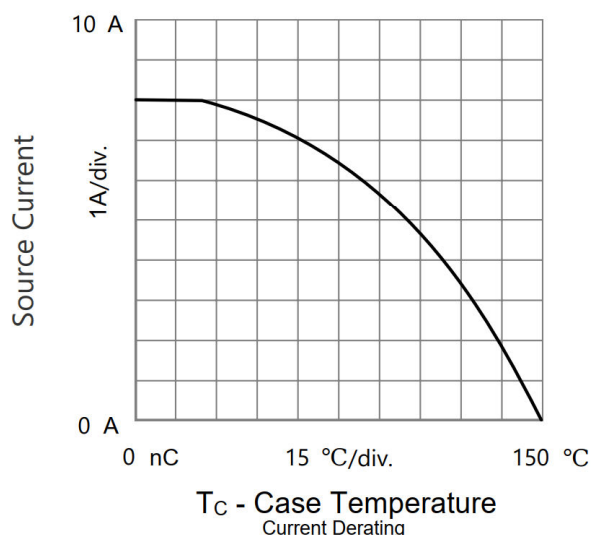
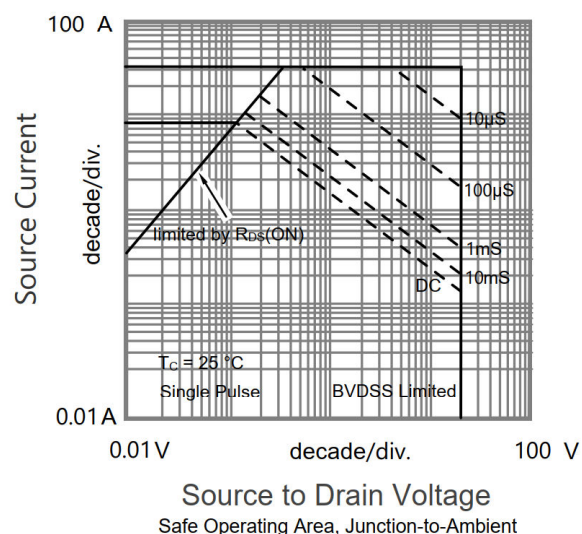
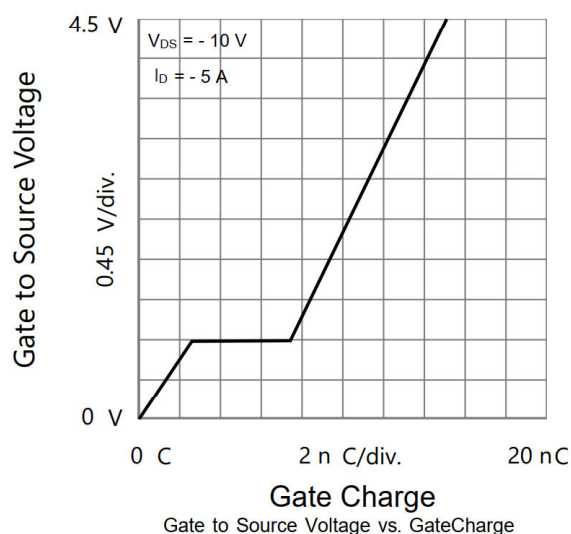


Source to Drain Voltage
Body Diode Forward Characteristics



Drain to Source Voltage
Capacitances

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



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